



Abstract

The invention relates to a method for incorporating a carrier element or module in a card body. The card body is provided with a recess shaped accordingly for incorporating the carrier element. The carrier element comprises a substrate on which an integrated circuit is disposed. Before the carrier element is incorporated a contact adhesive element is first introduced into the recess by means of a suitable tool. The carrier element can then be connected firmly and permanently with the card body with the aid of the contact adhesive element under the action of pressure.